April 28, 2011  CN 042811

Customer Notification
Alternate Pack and Ship Site for Waffle Pack Die Sales Products

Dear Valued Customer:

This notification is for the purpose of informing you of an additional facility for performing the backend services for Mindspeed’s die sales products.

**Purpose**

The purpose is to add a second backend location, Amkor Philippines, for the die sales products shown below. Currently Mindspeed utilizes Unisem Malaysia to waffle pack and ship these products. Mindspeed is implementing this additional site to increase capacity for waffle pack products and improve our assurance of the delivery of these products to our customers. There will be no changes to product dimensions, visual inspection criteria, or shipping containers.

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Description</th>
<th>Quantity</th>
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</thead>
<tbody>
<tr>
<td>M02006E-WP-T</td>
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<td>M02006F-WP-T</td>
<td></td>
<td></td>
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<tr>
<td>M02006-WP-T</td>
<td></td>
<td></td>
</tr>
<tr>
<td>M02007-3-WP-T</td>
<td></td>
<td></td>
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<td>M02009X-WP-T</td>
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**Change Schedule**

Customers may begin to receive products shipped from Amkor Philippines beginning on June 1, 2011. Product will also continue to ship from the current site, Unisem Malaysia.

**Method to identify parts**

The labels on the shipping containers identify Malaysia and Philippines, making it easy for our customers to identify which location the product was waffle packed and shipped.

**Customer Impact**

No customer impact is anticipated with this change; there is no change to form, fit, or function.

We are confident this change will allow Mindspeed Technologies to maintain its high standards for quality and reliability. We will be managing this change very closely to ensure minimum disruption to our customers. If, at any time, you have a need for further information, please contact your local Sales Representative.
Customer Notification
Alternate Pack and Ship Site for Waffle Pack Die Sales Products

The indicated Customer Notification letter was received and acknowledged by the undersigned authority.

Name: ________________________________
Signature: ________________________________
Print: ________________________________

Company: ________________________________
Name: ________________________________
Location: ________________________________

Title: ________________________________
Date: ________________________________

Comments/additional requests: ________________________________

Thank you for your attention on this matter.

Please return the acknowledgment form to the attention of Dan McCarville at Mindspeed Technologies Inc., 4000 MacArthur Blvd, Newport Beach, Ca, 92660; daniel.mccarville@mindspeed.com.